

SPECIFICATION AND PERFORMANCE

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|---------------|------------------|-------------|-------------------------|-------------|-------------------|
| Series | 115R-BCAO | File | 115R-BCAO_Spec_2 | Date | 2023/01/10 |
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Scope:

This specification covers the requirements for product performance, test methods and quality assurance provisions of **115R-BCAO**

Performance and Descriptions:

The product is designed to meet the electrical, mechanical and environmental performance requirements specification. Unless otherwise specified, all tests are performed at ambient environmental conditions.

RoHS:

All material in according with the RoHS environment related substances list controlled.

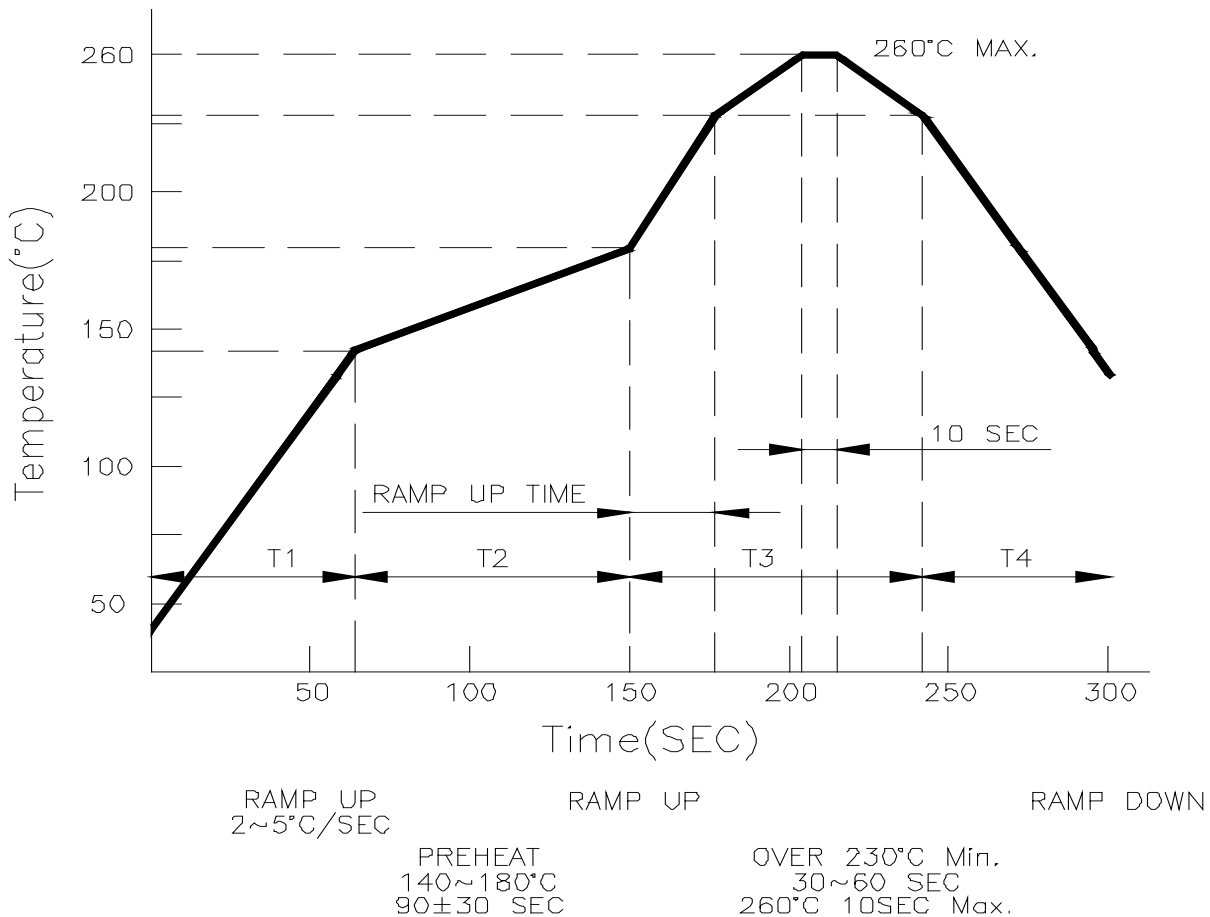
| MATERIAL AND FINISH | | |
|---------------------|---|---|
| INSULATOR | Material | Housing: LCP, Black |
| CONTACT | Material | Contact: Copper Alloy 0.08T Ground: Stainless 0.15T |
| | Plating | Contact: 5u" selective gold plating on contact and solder area Ground: G/F selective gold plating on solder area Under plating nickel |
| SHELL | Material | Stainless 0.12T |
| | Plating | 50u" nickel plating |
| RATING | Voltage & Current: 10V AC/ DC, 0.5A Max. Operating Temperature: -40°C to +85°C Storage Temperature: -40°C to +85°C Storage Humidity: +10%~ +80% RH | |

| ELECTRICAL | | |
|---------------------------------|--|---|
| Item | Requirement | Test Condition |
| Current Rating | Temperature rise: 30°C Max. Current: 0.5A Max. | Apply the rated current to connector, EIA 364-70 |
| Contact Resistance | Initially 50 mΩ Max. Finally 100 mΩ Max after test. | EIA-364-23C Mate connectors with dry circuit (20 mV, 100mA Max.) at 0.05mm away from housing top surface (see appendix 1) |
| Insulation Resistance | (Initial) 1000 MΩ Min. (Final) 500 MΩ Min. | EIA-364-21C After 500 VDC for 1 minute, measure the insulation resistance between the adjacent contacts of mated and unmated connector assemblies. |
| Dielectric Withstanding Voltage | No shorting, breakdown, flashover or other damage. | Comply with EIA-364-20. Apply 500 VAC for one minute at sea level on unmated connectors, less than 0.5 mA leakage current. |

| MECHANICAL | | |
|---|--|--|
| Item | Requirement | Test Condition |
| Contact Normal Force | 30gf Min./per Pin | 0mm gap to housing surface (work position) Speed of 0.60±3 mm/minute (0mm from housing) (refer to Appendix 2) |
| Durability (Vertical Insertion Direction) | Contact resistance Initially 50 mΩ Max. Contact resistance Finally 100 mΩ Max. Contact Normal Force within spec. (refer to Appendix 1&2) | Mate connectors at 240-550 cycles/hour to 3000 cycles. Vertical insertion for max deflection case. |
| Open & Lock Durability | Durability: 50 Cycles Final Force: 150g Min. | SIM card connector on the PCB welding, load a SIM card inside the connector, parallel to push on the shell surface for open & lock |

| ENVIRONMENTAL | | |
|----------------------------|---|---|
| Item | Requirement | Test Condition |
| LOW temperature resistance | Contact resistance 100mΩ Max. | At -30°C for 96 hours Recovery: 2 hours at ambient atmosphere |
| Humidity resistance | There shall be no short circuiting and damage detected at AC 500V r.m.s Insulation resistance: 1000MΩ Min. Contact resistance: 100mΩ Max. | EIA 364 - 31 Method II Test Condition A. Subject unmated connectors to 96 hours at 60°C with 90% to 95% R.H. |
| Temperature life | Resistance: 100mΩ Max. change from initial value | At +85°C for 96 hours |
| Salt Spray | Meets requirements of product drawing Contact resistance: 100mΩ Max. | EIA-364-26B Subject mated connectors to 5+/-1% salt-solution concentration, 35+/-2°C for 24hours. After test, rinse the sample with water and recondition the room temperature for 1 hour |
| Vibration (Random) | Contact resistance 100mΩ Max. Discontinuity < 1 ms | (EIA-364-28) Frequency: 10~100 Hz, 0.0132 g ² /Hz; Frequency: 100~500Hz, -3dB/Oct Applied for 1 hours in each 3 mutually perpendicular axes |
| Shock (specified pulse) | Contact resistance 100mΩ Max. Discontinuity < 1 ms | Pulse shape = half sine Peak acceleration = 490m/s ² (50G) Duration of pulse = 11ms Apply 3 successive shocks in each direction along the 3 mutually perpendicular axes. (EIA364-27) |

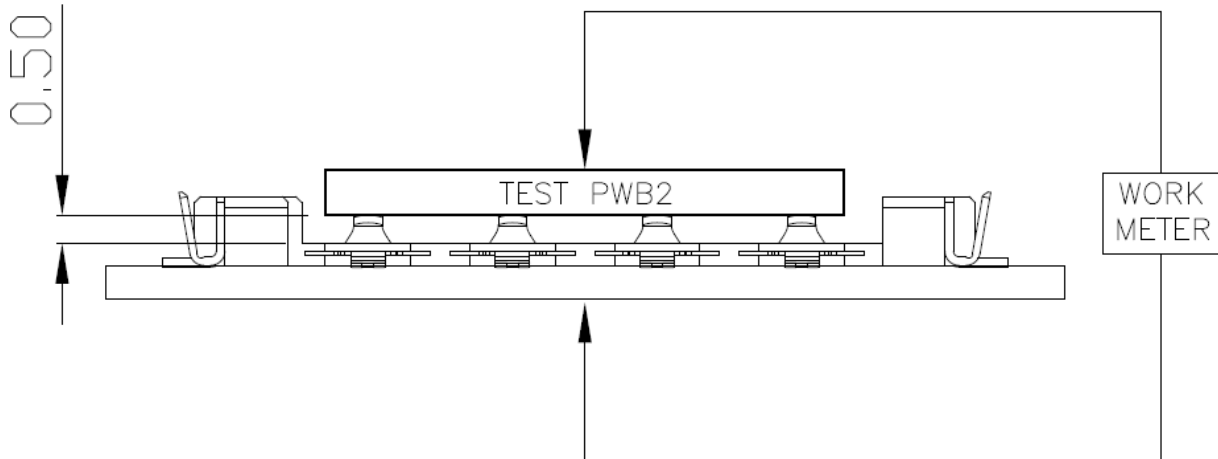
| SOLDER ABILITY | | |
|-----------------------------|--|---|
| Item | Requirement | Test Condition |
| Solder-ability | The inspected area of each lead must have 95% solder coverage min. | JESD22-B102D, Condition C Steam aging Preconditioning: 93+3/-5°C, 8 hours ±15 minute For SMT: Solder temperature: 245± 5°C. Solder immersion time: 5±0.5s |
| Soldering heat withstanding | Inspect dimension during the test, no physical damage | Reflow soldering (Infrared): Refer soldering method |

Recommended Infrared Reflow Condition:


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|-----|-------------------------------|------------|
| T1: | Temperature Ramp Up Rate | 2~5°C/SEC |
| T2: | Prehead: 140°C~180°C | 90±30 SEEC |
| T3: | Time Over 230°C | 30~60 SEC |
| T4: | Ramp Down Rate During Cooling | 4~7°C/SEC |
| | Pear Temperature | 260°Max. |

Fig.1

Appendix 1:
Contact Resistance Measurement



Appendix 2:
Card Insertion Directions in Durability:

